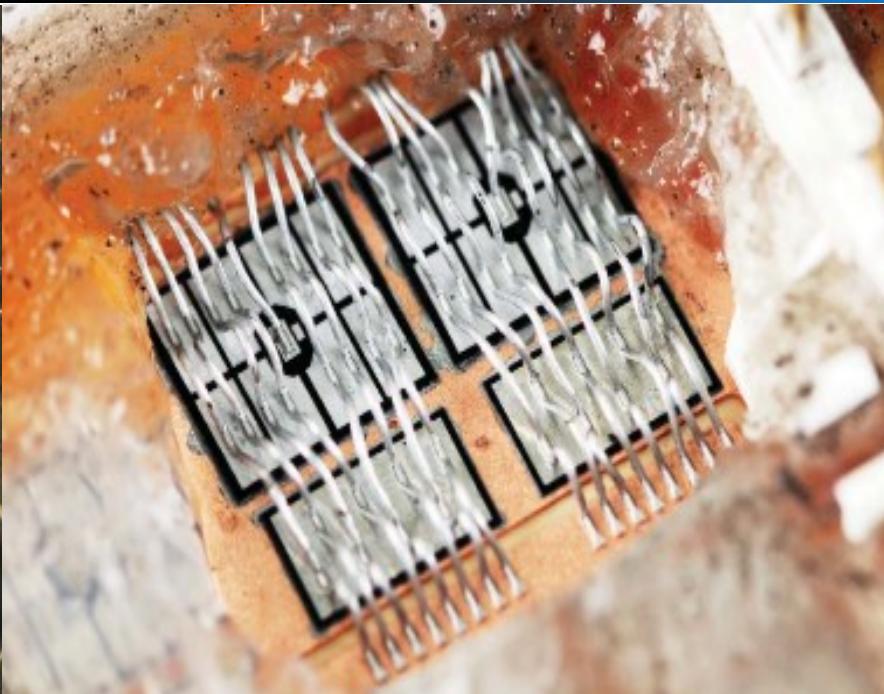
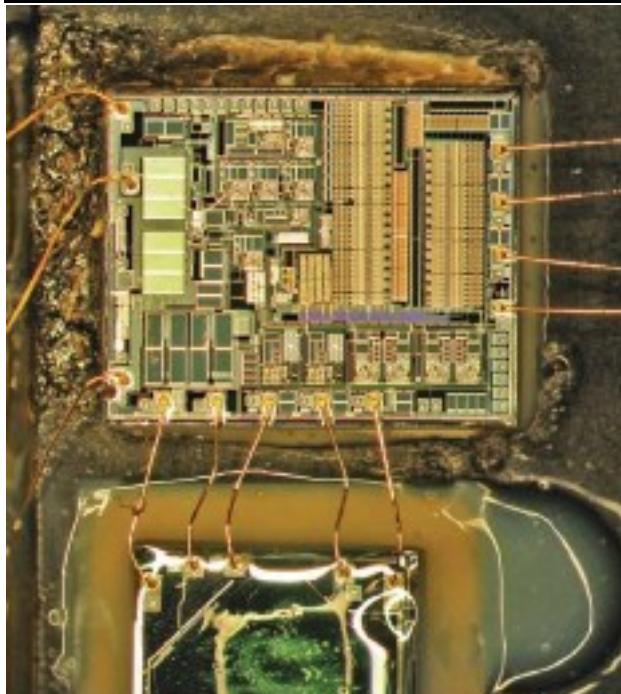


New Developments in Laser Failure Analysis Technology

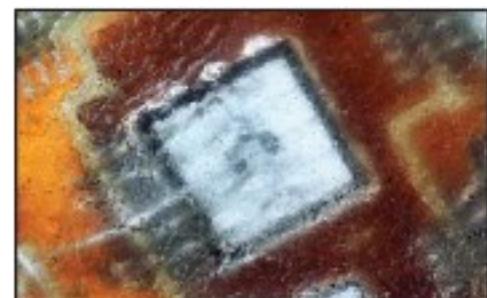
IC Gel Compound Removal



New Unique Gel Compound Removal Laser Technique

A growing number of IC design are utilizing GEL type encapsulation compounds. Whether it is for diaphragm on the die for pressure detection. Less stress on newer thinner dies, or extreme temperature variations faced by the automotive industry, this type of compound seems impervious to chemical, plasma, or even other laser decapsulation.

Until now! - Our FA-LIT Gel Decapsulation Process now safely removes Gel Compound **“ALL THE WAY DOWN TO THE DIE”** in seconds.



Gel Compound Covering IC



PATENTED LASER TECHNOLOGY
United States 7,271,012

Japan 4,843,488
China ZL200480022971.0
Philippines 1-2006-500131
Europe 04778639.7 (pending)
Canada 2,532,959 (pending)
Korea 10-2006-7000841 (pending)



Gel Removed with FA-LIT Laser

FALIT

Failure Analysis Laser Inspection Tool



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